

# EGPL-G2P1

## M.2 to Dual PoE Module

**Customer:** \_\_\_\_\_

**Customer** \_\_\_\_\_

**Part Number:** \_\_\_\_\_

**Innodisk** \_\_\_\_\_

**Part Number:** \_\_\_\_\_

**Innodisk** \_\_\_\_\_

**Model Name:** \_\_\_\_\_

**Date:** \_\_\_\_\_

<b>Innodisk Approver</b>	<b>Customer Approver</b>

## Table of Contents

<b>TABLE OF CONTENTS .....</b>	<b>I</b>
<b>REVISION HISTORY .....</b>	<b>II</b>
<b>LIST OF TABLES .....</b>	<b>1</b>
<b>LIST OF FIGURES .....</b>	<b>2</b>
<b>1. PRODUCT INTRODUCTION .....</b>	<b>3</b>
1.1. OVERVIEW .....	3
1.2. FEATURES .....	3
<b>2. PRODUCT SPECIFICATIONS .....</b>	<b>6</b>
2.1. DEVICE PARAMETERS .....	6
2.2. ELECTRICAL SPECIFICATIONS.....	6
2.2.1.POWER REQUIREMENT.....	6
2.2.2.POWER CONSUMPTION .....	6
2.3. ENVIRONMENTAL SPECIFICATIONS .....	6
2.3.1.TEMPERATURE RANGES.....	6
2.3.2.HUMIDITY .....	7
2.3.3.SHOCK AND VIBRATION .....	7
2.3.4.MEAN TIME BETWEEN FAILURE (MTBF) .....	7
2.4. CE AND FCC COMPATIBILITY.....	7
2.5. RoHS COMPLIANCE .....	7
2.6. HARDWARE.....	8
2.6.1.LAYOUT.....	8
2.6.2.PIN DEFINE .....	9
2.6.3.I/O CONNECTOR MECHANICAL DRAWING & PIN DEFINES .....	11
2.6.4.EGPL-G2P1 MECHANICAL DRAWING.....	13
2.6.5.CABLE MECHANICAL DRAWING.....	17
2.6.6.PACKING LIST .....	17
2.7. SOFTWARE SUPPORT.....	17
<b>3. INSTALLATION GUIDE .....</b>	<b>18</b>
<b>4. APPENDIX .....</b>	<b>19</b>
<b>CONTACT US .....</b>	<b>23</b>

## REVISION HISTORY

Revision	Description	Date
1.0	First Released	Jun, 2019

## List of Tables

<b>TABLE 1: DEVICE PARAMETERS .....</b>	<b>6</b>
<b>TABLE 2: POWER REQUIREMENT.....</b>	<b>6</b>
<b>TABLE 3: POWER CONSUMPTION .....</b>	<b>6</b>
<b>TABLE 4: TEMPERATURE RANGES.....</b>	<b>6</b>
<b>TABLE 5: SHOCK AND VIBRATION .....</b>	<b>7</b>
<b>TABLE 6: MEAN TIME BETWEEN FAILURE (MTBF).....</b>	<b>7</b>
<b>TABLE 7: M.2 2280 PCB LAYOUT LEGEND.....</b>	<b>8</b>
<b>TABLE 8: DAUGHTER BOARD PCB LAYOUT LEGEND .....</b>	<b>8</b>
<b>TABLE 9: M.2 B-M KEY PIN DEFINE .....</b>	<b>9</b>
<b>TABLE 10: 4PIN HEADER POWER INPUT PIN DEFINE .....</b>	<b>10</b>
<b>TABLE 11: WIRE TO BOARD SMD 2*10P CONNECTOR PIN DEFINE.....</b>	<b>11</b>
<b>TABLE 12: RJ45 LAN LED TABLE.....</b>	<b>13</b>

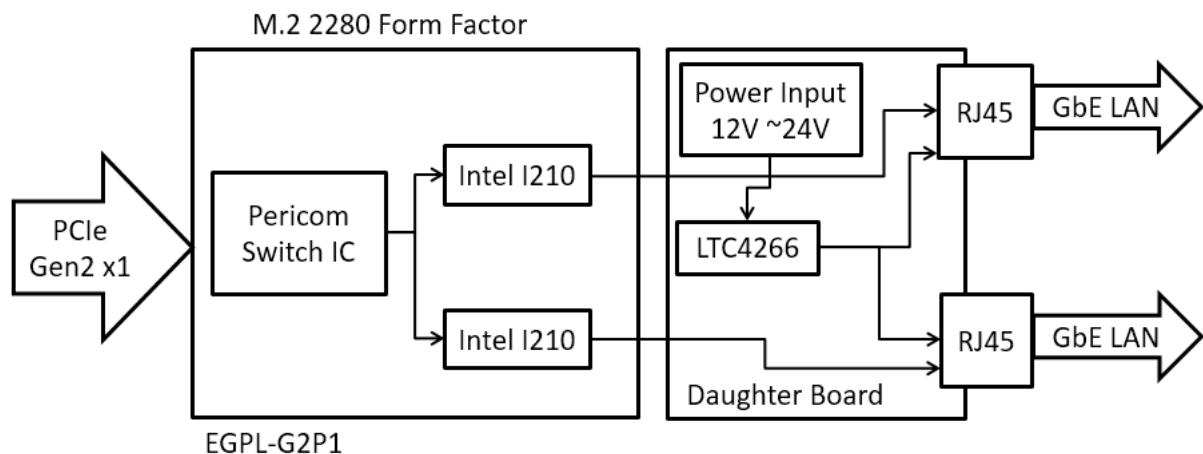
## List of Figures

<b>FIGURE 1: BLOCK DIAGRAM .....</b>	<b>3</b>
<b>FIGURE 2: M.2 2280 BOARD PICTURE.....</b>	<b>4</b>
<b>FIGURE 3: MOUNTING HOLE, 4PIN HEADER, DAUGHTER BOARD PICTURE (EGPL-G2P1-C1/W1) ...</b>	<b>4</b>
<b>FIGURE 4: BRACKET, 4PIN HEADER, DAUGHTER BOARD PICTURE (EGPL-G2P1-C2/W2) .....</b>	<b>4</b>
<b>FIGURE 5: MOUNTING HOLE, DC JACK, DAUGHTER BOARD PICTURE (EGPL-G2P1-C3/W3) .....</b>	<b>5</b>
<b>FIGURE 6: BRACKET, DC JACK, DAUGHTER BOARD PICTURE (EGPL-G2P1-C4/W4) .....</b>	<b>5</b>
<b>FIGURE 7: WIRE TO BOARD SMD 2*10P CONNECTOR DRAWING .....</b>	<b>11</b>
<b>FIGURE 8: RJ45 CONNECTOR DRAWING .....</b>	<b>12</b>
<b>FIGURE 9: EGLP-G2P1 M.2 BOARD DRAWING .....</b>	<b>13</b>
<b>FIGURE 10: MOUNTING HOLE DAUGHTER BOARD DRAWING - 4PIN HEADER (EGPL-G2P1-C1/W1)</b> .....	<b>14</b>
<b>FIGURE 11: BRACKET DAUGHTER BOARD DRAWING - 4PIN HEADER (EGPL-G2P1-C2/W2) .....</b>	<b>14</b>
<b>FIGURE 12: MOUNTING HOLE DAUGHTER BOARD DRAWING – DC JACK (EGPL-G2P1-C3/W3) ....</b>	<b>15</b>
<b>FIGURE 13: BRACKET DAUGHTER BOARD DRAWING – DC JACK (EGPL-G2P1-C4/W4).....</b>	<b>15</b>
<b>FIGURE 14: BRACKET DRAWING .....</b>	<b>16</b>
<b>FIGURE 15: BRACKET + DC JACK DRAWING.....</b>	<b>16</b>
<b>FIGURE 16: BOARD TO BOARD LAN CABLE DRAWING.....</b>	<b>17</b>

# 1. Product Introduction

## 1.1. Overview

Innodisk EGLP-G2P1 is M.2 2280 B/M key form factor PoE card which supports dual GbE 802.33af(PoE) compliant Ethernet ports. With 12V~24V power input via 4pin header or DC Jack, the EGLP-G2P1 can provide up to 15.4 watts at 48 VDC power to dual ports at same time. It allows power to be supplied to powered devices, such like PoE IP camera or PoE Wifi AP, which brings you a flexible expansion solution for embedded systems.



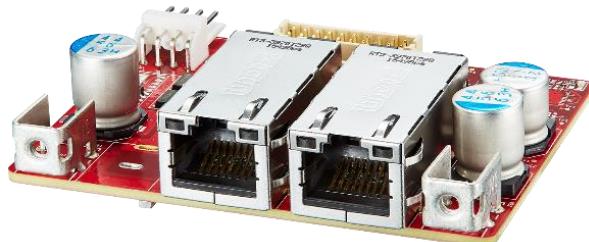
**Figure 1: Block Diagram**

## 1.2. Features

- Supports dual GbE LAN ports
- Two independent PSE channels
- Supports 12V~24V power input via 4pin header or DC Jack
- Complies with IEEE 802.3af, up to 15.4W at 48V per PoE port
- Complies with EN61000-4-2 (ESD) Air-15kV, Contact-8kV
- Industrial temperature -40 °C to 85 °C



**Figure 2: M.2 2280 Board Picture**



**Figure 3: Mounting Hole, 4Pin Header, Daughter Board Picture (GPL-G2P1-C1/W1)**



**Figure 4: Bracket, 4Pin Header, Daughter Board Picture (GPL-G2P1-C2/W2)**



**Figure 5: Mounting Hole, DC Jack, Daughter Board Picture (EGPL-G2P1-C3/W3)**



**Figure 6: Bracket, DC Jack, Daughter Board Picture (EGPL-G2P1-C4/W4)**

## 2. Product Specifications

### 2.1. Device Parameters

**Table 1: Device Parameters**

<b>Form Factor</b>	M.2 2280 B-M
<b>Input I/F</b>	PCI Express 2.1 x 1
<b>Output I/F</b>	PoE LAN x 2
<b>Output Connector</b>	RJ45 x 2
<b>Dimension (WxLxH)</b>	M.2 Board: 22 x 80 x 7.1 mm Daughter Board: 72.7 x 58.2 x 23.6 mm

### 2.2. Electrical Specifications

#### 2.2.1. Power Requirement

**Table 2: Power Requirement**

Item	Connector	Rating
Main Board	M.2 Golden Finger	+3.3 VDC +-5%
Daughter Board	4Pin Header/ DC Jack	12 ~ 24 VDC

#### 2.2.2. Power Consumption

**Table 3: Power Consumption**

	Full Load (mA)	Voltage (V)
Main Board	450	3.3
Daughter Board	1250	24

### 2.3. Environmental Specifications

#### 2.3.1. Temperature Ranges

**Table 4: Temperature Ranges**

Temperature	Range
Operating	Standard Grade: 0°C to +70°C Industrial Grade: -40°C to +85°
Storage	-55°C to +95°

### 2.3.2. Humidity

Relative Humidity: 10-95%, non-condensing

### 2.3.3. Shock and Vibration

**Table 5: Shock and Vibration**

Reliability	Test Conditions	Reference Standards
Vibration	7 Hz to 2K Hz, 20G, 3 axes	IEC 68-2-6
Mechanical Shock	Duration: 0.5ms, 1500 G, 3 axes	IEC 68-2-27

### 2.3.4. Mean Time between Failure (MTBF)

Reliability prediction methodology provides the basis for reliability evaluation and analysis. The purpose of the prediction is to predict the life time of the product in units of failure rate and MTBF.

**Table 6: Mean Time between Failure (MTBF)**

Product	Condition	MTBF (Hours)
GPL-G2P1	The analysis is at 25°C ambient temperature by Telcordia SR-332, Issues 4, Method I, Case 3 under Ground Benign, Controlled environment, 50% operation stress	TBD

### 2.4. CE and FCC Compatibility

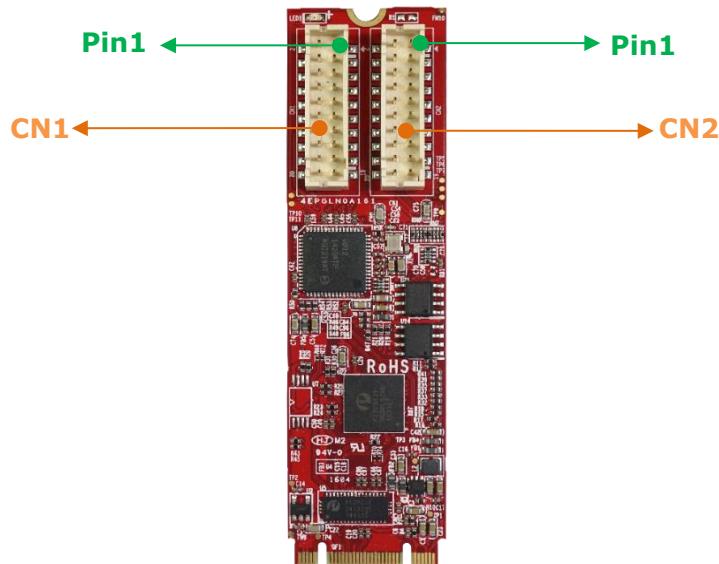
GPL-G2P1 conforms to CE and FCC requirements.

### 2.5. RoHS Compliance

GPL-G2P1 is fully compliant with RoHS directive.

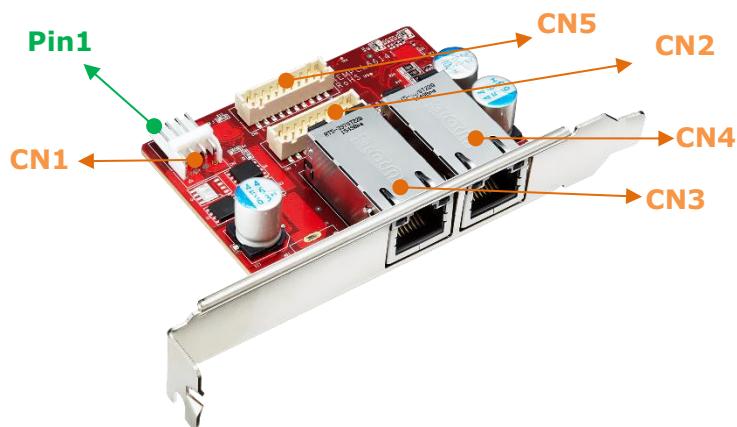
## 2.6. Hardware

### 2.6.1. Layout



**Table 7: M.2 2280 PCB Layout Legend**

Label	Connector Type	Function
<b>CN1/ CN2</b>	Wire to board SMD 2*10P 180° P:2.00mm H:4.0mm	GbE LAN Signal 10/100/1000 LED Signal



**Table 8: Daughter Board PCB Layout Legend**

Label	Connector Type	Function
<b>CN1</b>	4Pin Header	4Pin Header Power Input

<b>CN3/ CN4</b>	10/100/1000 Base-T RJ45 PoE DIP 16P16C 90° LED: Green-Orange/Green	PoE GbE LAN Port 10/100/1000 LED Indicator
<b>CN2/ CN5</b>	Wire to board SMD 2*10P 180° P:2.00mm H:4.0mm	GbE LAN Signal 10/100/1000 LED Signal

## 2.6.2. Pin Define

**Table 9: M.2 B-M Key Pin Define**

Signal Name	Pin #	Pin #	Signal Name
		<b>75</b>	NC
3.3V	<b>74</b>	<b>73</b>	GND
3.3V	<b>72</b>	<b>71</b>	GND
3.3V	<b>70</b>	<b>69</b>	NC
NC	<b>68</b>	<b>67</b>	RESET#

## Module Key M

NC	<b>58</b>		
NC	<b>56</b>	<b>57</b>	GND
PE_WAKE_N	<b>54</b>	<b>55</b>	CLK+
GND	<b>52</b>	<b>53</b>	CLK-
PE_RST	<b>50</b>	<b>51</b>	GND
NC	<b>48</b>	<b>49</b>	RX+
NC	<b>46</b>	<b>47</b>	RX-
NC	<b>44</b>	<b>45</b>	GND
NC	<b>42</b>	<b>43</b>	TX+
NC	<b>40</b>	<b>41</b>	TX-
NC	<b>38</b>	<b>39</b>	GND
NC	<b>36</b>	<b>37</b>	NC
NC	<b>34</b>	<b>35</b>	NC
NC	<b>32</b>	<b>33</b>	GND
NC	<b>30</b>	<b>31</b>	NC
NC	<b>28</b>	<b>29</b>	NC
NC	<b>26</b>	<b>27</b>	GND
NC	<b>24</b>	<b>25</b>	NC

NC	<b>22</b>	<b>23</b>	NC
NC	<b>20</b>	<b>21</b>	NC
<b>Module Key B</b>			
NC	<b>10</b>	<b>11</b>	GND
NC	<b>8</b>	<b>9</b>	NC
NC	<b>6</b>	<b>7</b>	NC
3.3V	<b>4</b>	<b>5</b>	GND
3.3V	<b>2</b>	<b>3</b>	GND
		<b>1</b>	NC

**Table 10: 4Pin Header Power Input Pin Define**

Pin #	Signal Name
<b>1</b>	NC
<b>2</b>	GND
<b>3</b>	GND
<b>4</b>	12V-24V

### 2.6.3. I/O Connector Mechanical Drawing & Pin Defines

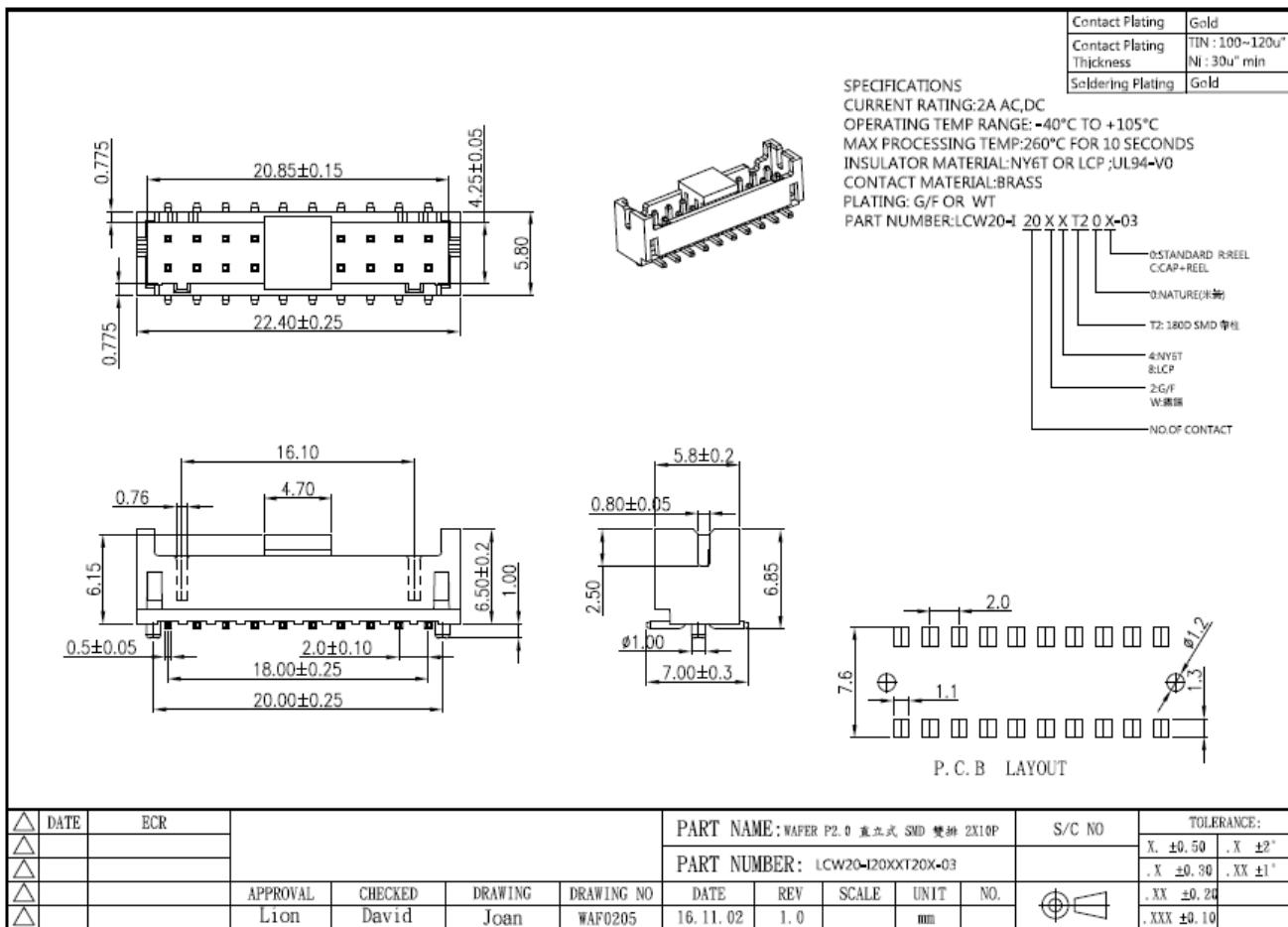


Figure 7: Wire to Board SMD 2\*10P Connector Drawing

Table 11: Wire to Board SMD 2\*10P Connector Pin Define

Signal Name	Pin #	Pin #	Signal Name
LINK_100_N	<b>2</b>	<b>1</b>	MDIOP_IC
LINK_ACT_N	<b>4</b>	<b>3</b>	MDION_IC
LINK_1000_N	<b>6</b>	<b>5</b>	MDI1P_IC
GND	<b>8</b>	<b>7</b>	MDI1N_IC
GND	<b>10</b>	<b>9</b>	MDI2P_IC
GND	<b>12</b>	<b>11</b>	MDI2N_IC
3.3V	<b>14</b>	<b>13</b>	MDI3P_IC
3.3V	<b>16</b>	<b>15</b>	MDI3N_IC
NC	<b>18</b>	<b>17</b>	NC
NC	<b>20</b>	<b>19</b>	NC

## 1. MECHANICAL DIMENSION

### 1.1 Product Dimension

General Tolerance: X.X :  $\pm 0.38$   
X.XX :  $\pm 0.20$

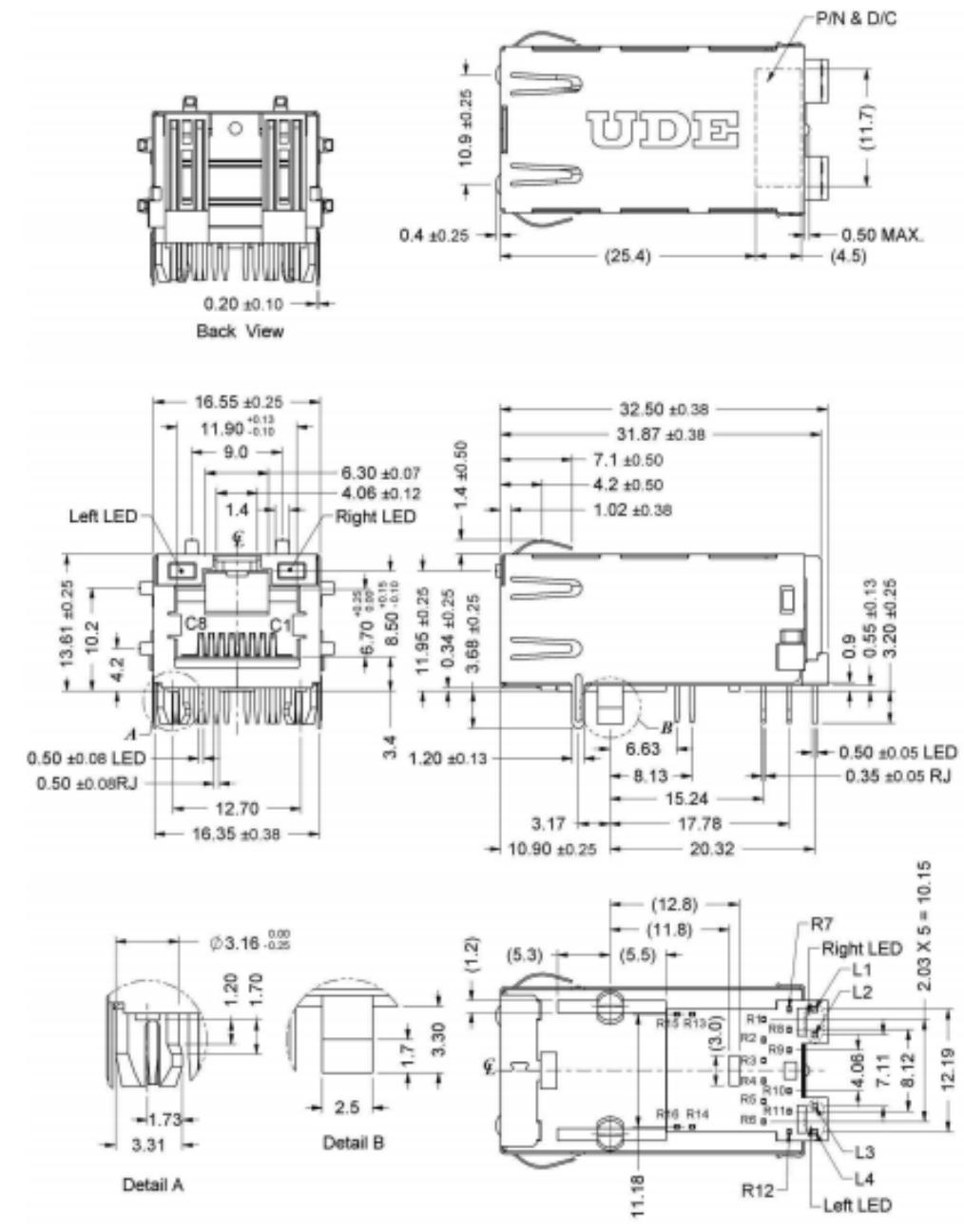
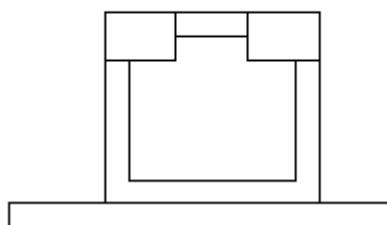


Figure 8: RJ45 Connector Drawing

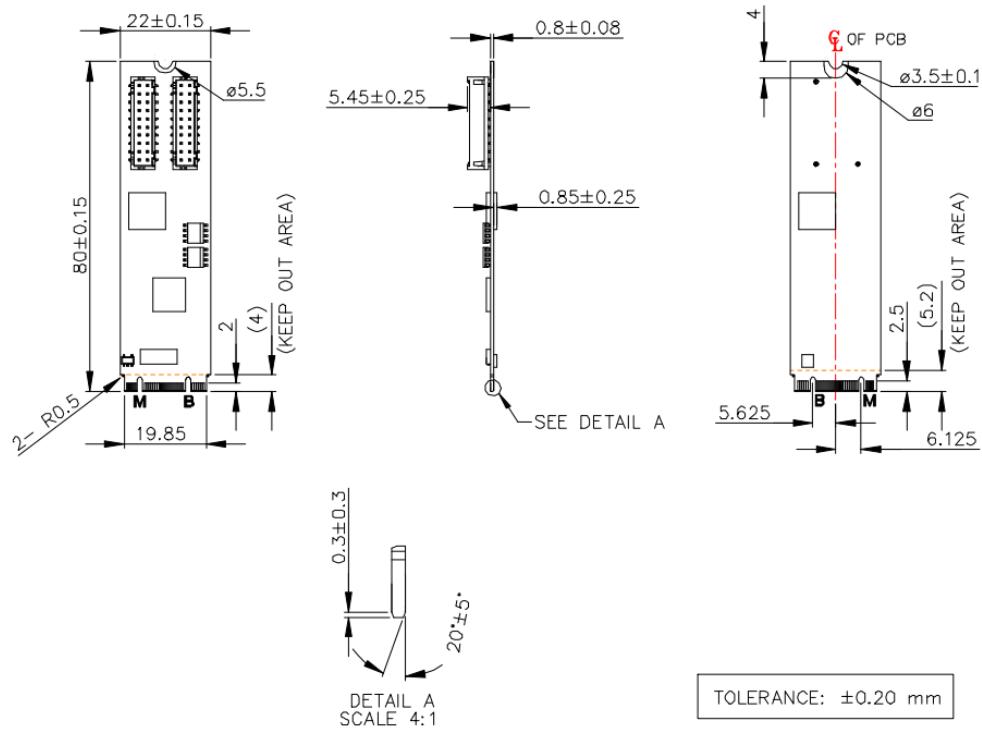
**Table 12: RJ45 LAN LED Table**

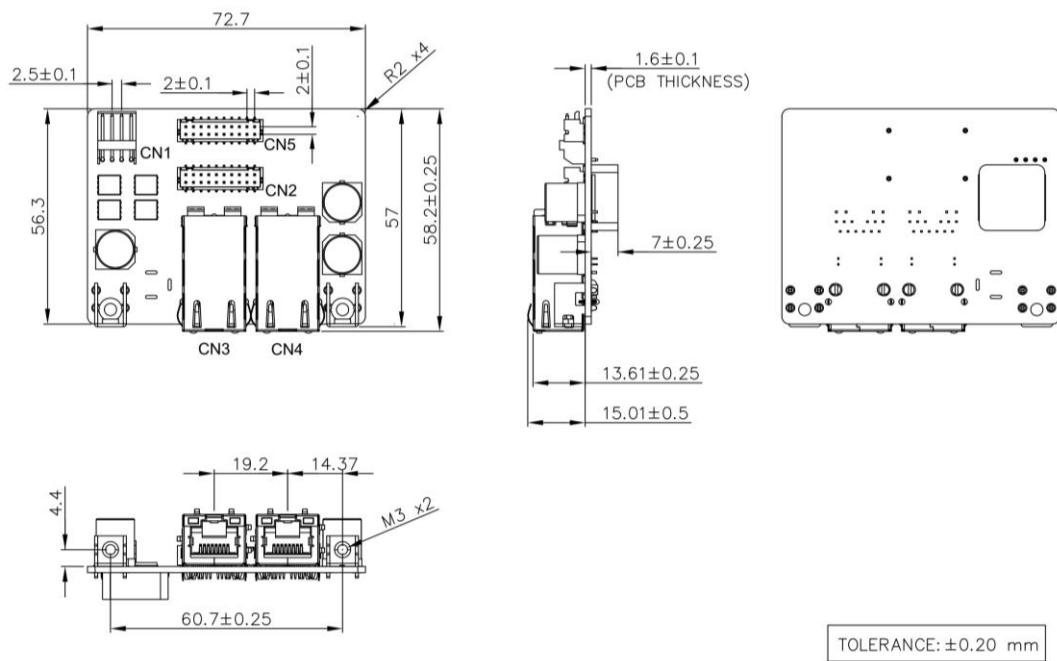
Orange  
/Green      Green



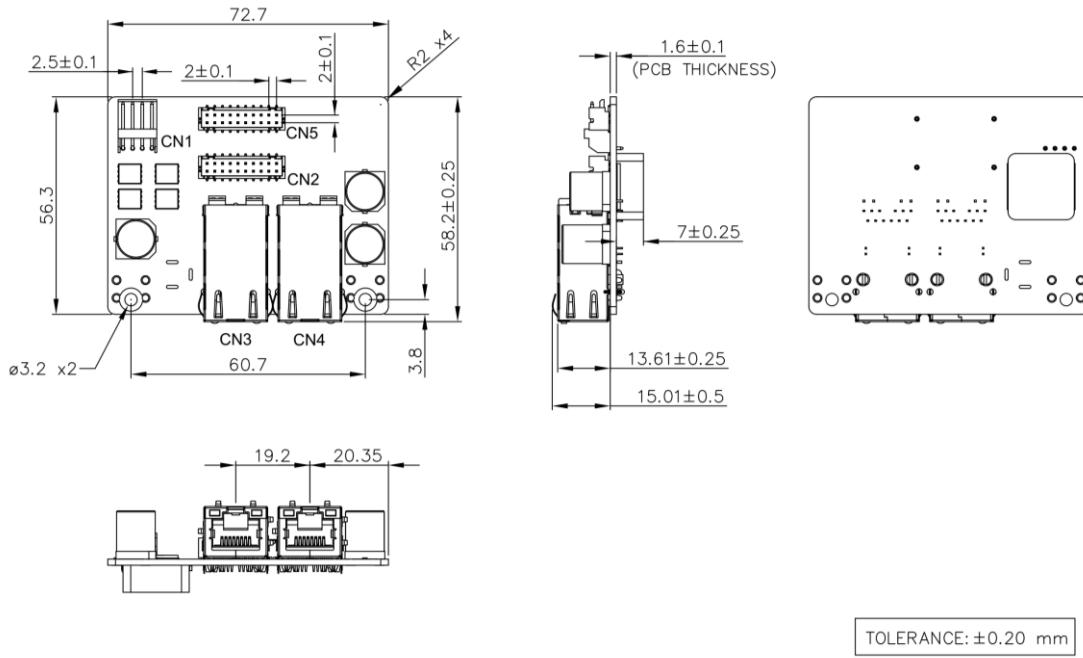
<b>Speed</b>	<b>Orange/Green (Status)</b>	<b>Green (Active/Link)</b>
<b>10M</b>	OFF	Flash
<b>100M</b>	ON (Green)	Flash
<b>1G</b>	ON (Orange)	Flash

#### 2.6.4. EGLP-G2P1 Mechanical Drawing

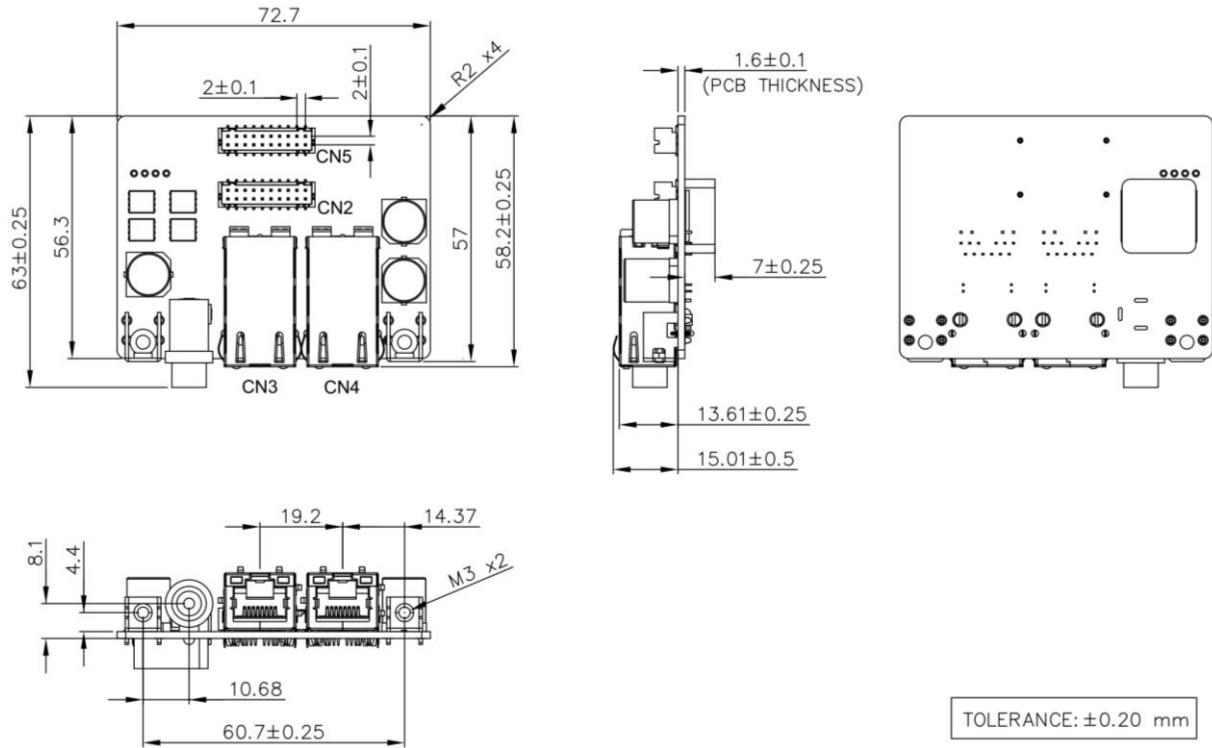
**Figure 9: EGLP-G2P1 M.2 Board Drawing**



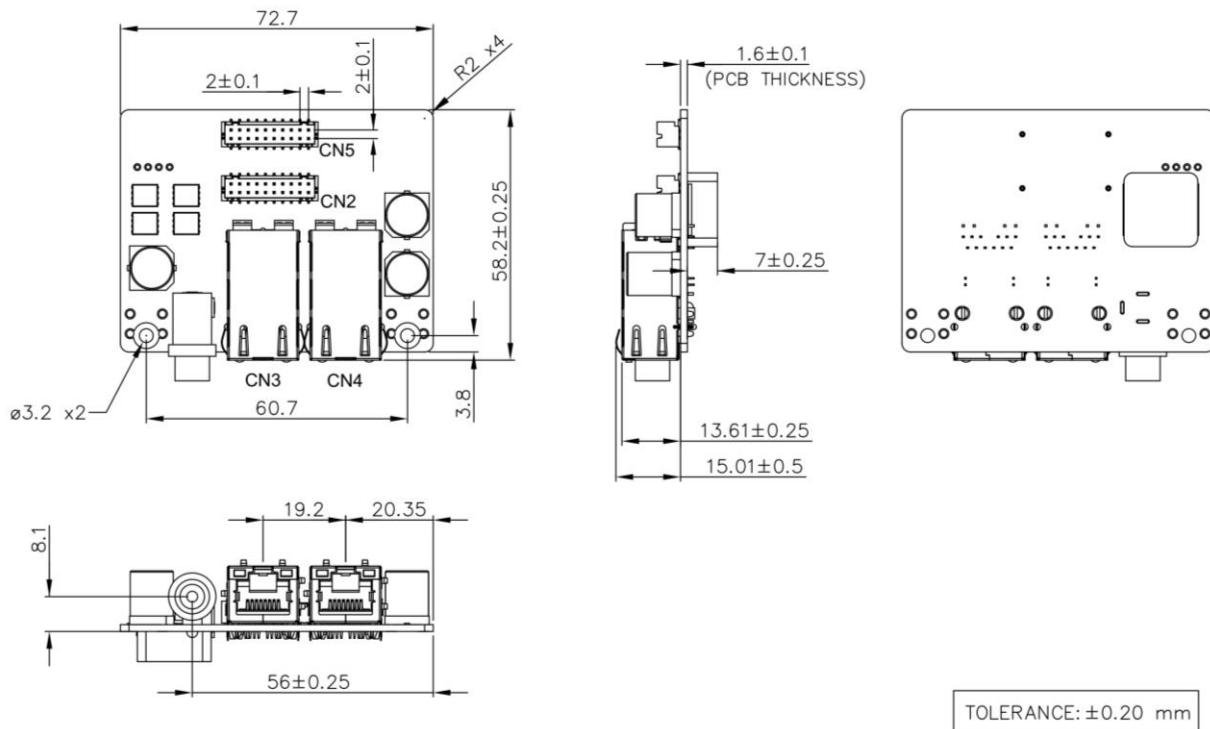
**Figure 10: Mounting Hole Daughter Board Drawing - 4Pin Header (EGPL-G2P1-C1/W1)**



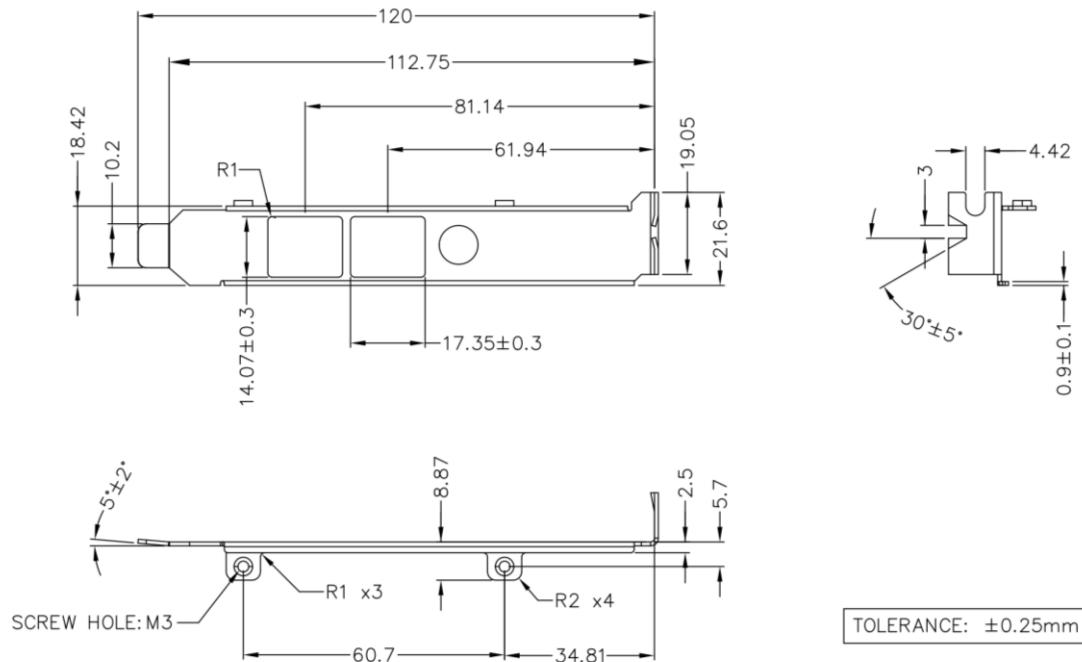
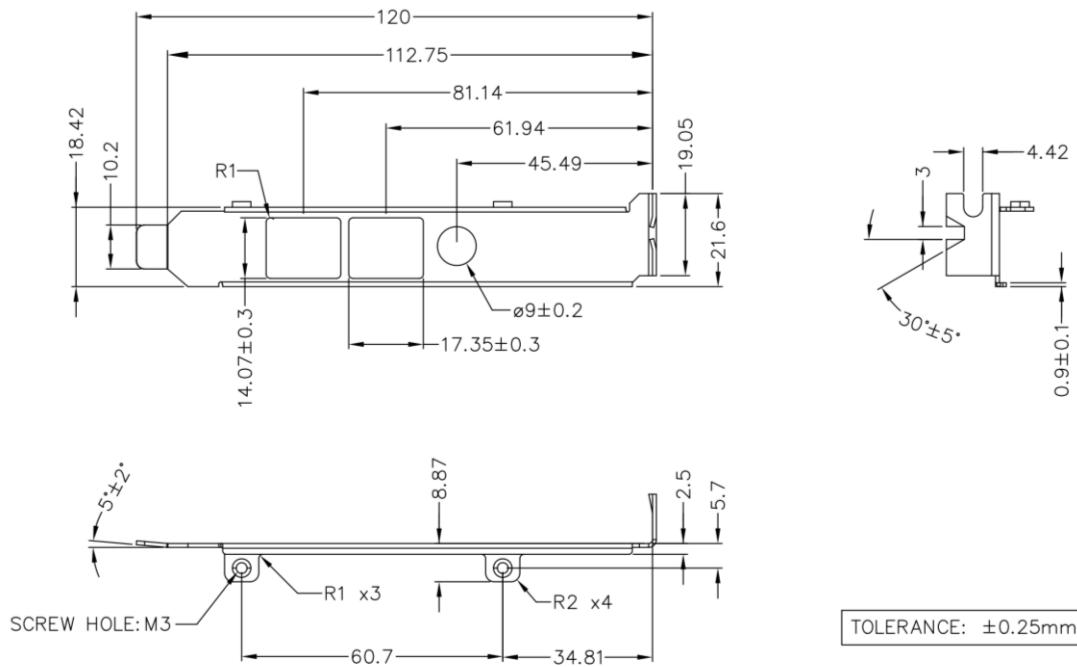
**Figure 11: Bracket Daughter Board Drawing - 4Pin Header (EGPL-G2P1-C2/W2)**



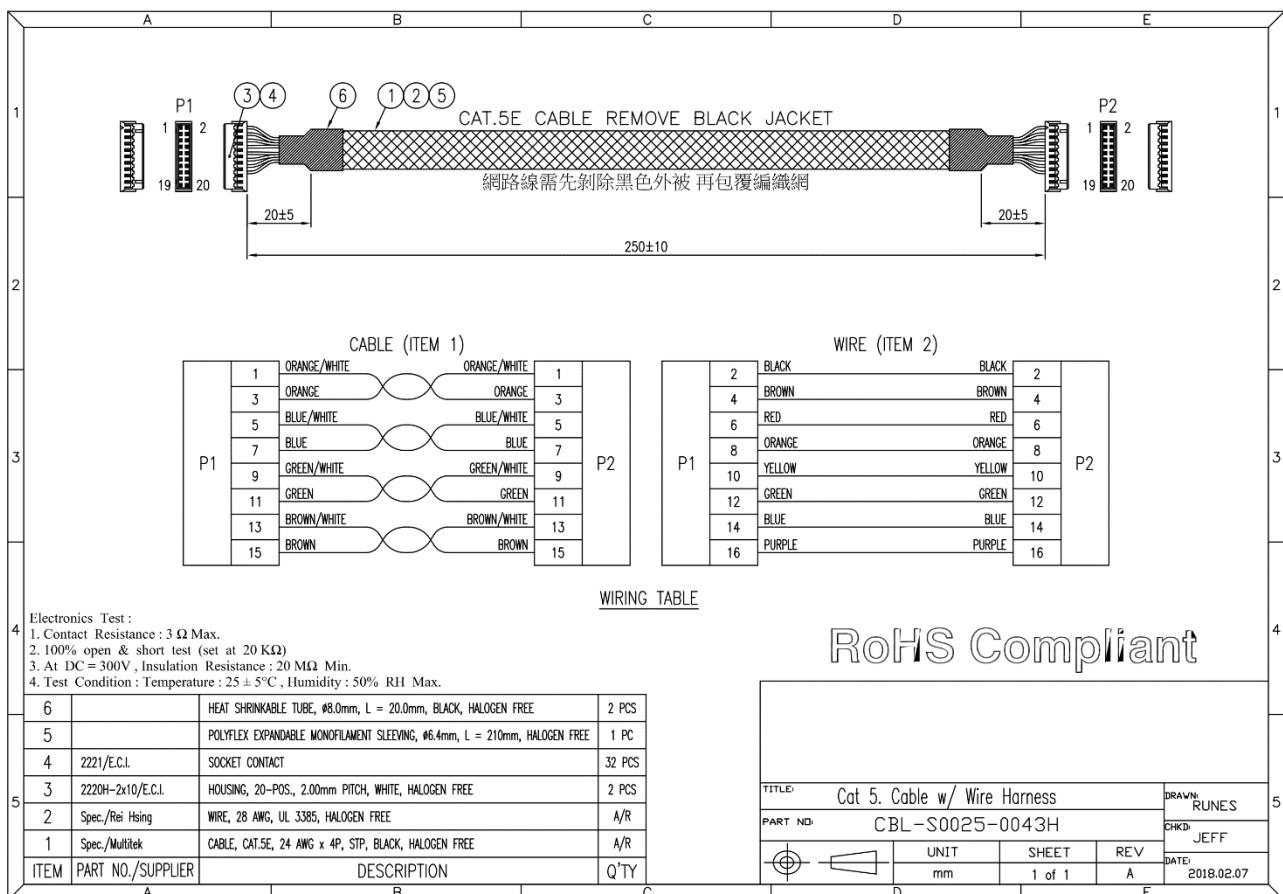
**Figure 12: Mounting Hole Daughter Board Drawing – DC Jack (EGPL-G2P1-C3/W3)**



**Figure 13: Bracket Daughter Board Drawing – DC Jack (EGPL-G2P1-C4/W4)**

**Figure 14: Bracket Drawing****Figure 15: Bracket + DC Jack Drawing**

## 2.6.5. Cable Mechanical Drawing



**Figure 16: Board to Board LAN Cable Drawing**

## 2.6.6. Packing List

- EGLP-G2P1 M.2 Board x 1
- EGLP-G2P1 Daughter Board x 1
- Board to Board LAN Cable x 2
- Bracket x 1 (EGLP-G2P1-C2/W2/C4/W4 only)
- Screw M3\*5 Silver x 2 (EGLP-G2P1 C2/W2/C4/W4 only)

## 2.7. Software Support

- Windows: XP(32bit), 7(32/64bit), 8/8.1(32/64 bit), 10(32/64bit)
- Linux: Kernel 2.4 above.

## 3. Installation Guide

Please download driver from Myinnodisk web site.

<https://myinnodisk.innodisk.com/myinnodisk/Login.aspx>

Or you can download intel i210 chip driver from intel official web site directly.

<https://downloadcenter.intel.com/product/64399/Intel-Ethernet-Controller-I210-Series>

## 4. Appedix

innodisk

宜鼎國際股份有限公司  
Innodisk Corporation  
REACH Declaration

Tel:(02)7703-3000 Fax:(02) 7703-3555 Internet: <http://www.innodisk.com/>

We hereby confirm that the product(s) delivered to

Innodisk P/N	Description
All Innodisk EP Products	

- contain(s) no hazardous substances or constituents exceeding the defined threshold 0.1 % by weight in homogenous material if not otherwise specified, as described in the candidate list table currently including 191 substances and shown on the ECHA website (<http://echa.europa.eu/de/candidate-list-table>).
- contain(s) one or more hazardous substances or constituents exceeding 0.1 % by weight in homogenous material if not otherwise specified in candidate list table. Where the threshold value is exceeded, the substances in question are to be declared in accompanying Appendix A & B.

### Guarantor

Company name 公司名稱：Innodisk Corporation 宜鼎國際股份有限公司

Company Representative 公司代表人：Randy Chien 簡川勝

Company Representative Title 公司代表人職稱：Chairman 董事長

Date 日期：2018 / 07 / 27



### RoHS 自我宣告書 (RoHS Declaration of Conformity)

#### Manufacturer Product: All Innodisk EP products

一、 宣鼎國際股份有限公司（以下稱本公司）特此保證售予貴公司之所有產品，皆符合歐盟 2011/65/EU 及(EU) 2015/863 關於 RoHS 之規範要求。

Innodisk Corporation declares that all products sold to the company, are complied with European Union RoHS Directive (2011/65/EU) and (EU) 2015/863 requirement.

二、 本公司同意因本保證書或與本保證書相關事宜有所爭議時，雙方宜友好協商，達成協議。

Innodisk Corporation agrees that both parties shall settle any dispute arising from or in connection with this Declaration of Conformity by friendly negotiations.

Name of hazardous substance	Limited of RoHS ppm (mg/kg)
鉛 (Pb)	< 1000 ppm
汞 (Hg)	< 1000 ppm
鎘 (Cd)	< 100 ppm
六價鉻 (Cr 6+)	< 1000 ppm
多溴聯苯 (PBBs)	< 1000 ppm
多溴二苯醚 (PBDEs)	< 1000 ppm
鄰苯二甲酸二(2-乙基己基)酯 (DEHP)	< 1000 ppm
鄰苯二甲酸丁醯苯甲酯 (BBP)	< 1000 ppm
鄰苯二甲酸二丁酯 (DBP)	< 1000 ppm
鄰苯二甲酸二異丁酯 (DIBP)	< 1000 ppm

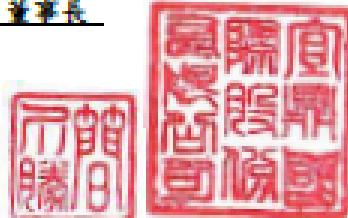
#### 立 保 壓 書 人 (Guarantor)

Company name 公司名稱 : Innodisk Corporation 宣鼎國際股份有限公司

Company Representative 公司代表人 : Randy Chien 簡川勝

Company Representative Title 公司代表人職稱 : Chairman 董事長

Date 日期 : 2018 / 07 / 01



# Certificate

Issue Date: December 2, 2016  
 Ref. Report No. ISL-16LE568CE

Product Name : mPCIe to dual GbE PoE Module  
 Model(s) : E%PL-G#P1  
 (%: Form factor: (2: 2.5"SSD,3:DDR3  
 DIMM,D:Dongle,G:NGFF\_M.2,H:mPCIe Half,L:PCIe Low  
 profile,M:mPCIe,S:PCIe Standard,X:Multi,Z:Others)  
 #: Output items: ( 1:1Port,2:2Ports,3:3Ports,4:4Ports,A~Z:TBD,X:Multi)  
 Responsible Party : Innodisk Corporation  
 Address : 5F., No.237, Sec. 1, Datong Rd., Xizhi Dist., New Taipei City 221, Taiwan  
 (R.O.C.)

We, **International Standards Laboratory**, hereby certify that:

The device bearing the trade name and model specified above has been shown to comply with the applicable technical standards as indicated in the measurement report and was tested in accordance with the measurement procedures specified in European Council Directive- EMC Directive 2014/30/EU. The device was passed the test performed according to :



**Standards:**

EN 55032:2015 and CISPR 32:2015  
 AS/NZS CISPR 32:2015  
 EN 61000-3-2:2014 and IEC 61000-3-2:2014  
 EN 61000-3-3: 2013 and IEC 61000-3-3: 2013  
 EN 55024: 2010+A1:2015 and CISPR 24: 2010+A1:2015  
 EN 61000-4-2: 2009 and IEC 61000-4-2: 2008  
 EN 61000-4-3: 2006+A1: 2008 +A2: 2010 and  
 IEC 61000-4-3:2006+A1: 2007+A2: 2010  
 EN 61000-4-4:2012 and IEC 61000-4-4:2012  
 EN 61000-4-5: 2014 and IEC 61000-4-5: 2014  
 EN 61000-4-6:2014+AC:2015 and IEC 61000-4-6:2013  
 EN 61000-4-8: 2010 and IEC 61000-4-8: 2009  
 EN 61000-4-11: 2004 and IEC 61000-4-11: 2004

I attest to the accuracy of data and all measurements reported herein were performed by me or were made under my supervision and are correct to the best of my knowledge and belief. I assume full responsibility for the completeness of these measurements and vouch for the qualifications of all persons taking them.

**International Standards Laboratory**

W.H. Chang / Director

**Hsi-Chih LAB:**

No. 65, Gu Dai Keng Street, Hsi-Chih Dist.,  
 New Taipei City 221, Taiwan  
 Tel: 886-2-2646-2550; Fax: 886-2-2646-4641



**Lung-Tan LAB:**

No. 120, Lane 180, Hsin Ho Rd., Lung-Tan Dist.,  
 Tao Yuan City 325, Taiwan  
 Tel: 886-3-407-1718; Fax: 886-3-407-1738



# Certificate

Issue Date: December 2, 2016  
 Ref. Report No. ISL-16LE568FA

Product Name : mPCIe to dual GbE PoE Module  
 Model(s) : E%PL-G#P1  
               (%: Form factor: (2: 2.5"SSD,3:DDR3 DIMM,D:Dongle,G:NGFF\_M.2,H:mPCIe  
               Half,L:PCIe Low profile,M:mPCIe,S:PCIe Standard,X:Multi,Z:Others)  
               #: Output items: ( 1:1Port,2:2Ports,3:3Ports,4:4Ports,A~Z:TBD,X:Multi)  
 Applicant : Innodisk Corporation  
 Address : 5F., No.237, Sec. 1, Datong Rd., Xizhi Dist., New Taipei City 221, Taiwan  
               (R.O.C.)

We, **International Standards Laboratory**, hereby certify that:

The device bearing the trade name and model specified above has been shown to comply with the applicable technical standards as indicated in the measurement report and was tested in accordance with the measurement procedures specified. (refer to Test Report if any modifications were made for compliance).



**Standards:**

FCC CFR Title 47 Part 15 Subpart B: 2015- Section 15.107 and 15.109

ANSI C63.4-2014

Industry Canada Interference-Causing Equipment Standard ICES-003 Issue 6: 2016

**Class A**

I attest to the accuracy of data and all measurements reported herein were performed by me or were made under my supervision and are correct to the best of my knowledge and belief. I assume full responsibility for the completeness of these measurements and vouch for the qualifications of all persons taking them.

**International Standards Laboratory**

W.H. Chang / Director

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December 28, 2022